



EDFAS 2022 BOARD OF DIRECTORS



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 Administrative Assistant

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 Dr. James Demarest, FASM
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Position

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 Event Chair

Affiliation

PrimeNano Inc
 NASA
 Materials Analytical Services
 IBM
 IBM

2022 ORGANIZING COMMITTEE



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Dr. Yan Li
Technical Program
Intel

ACTIVITIES CHAIRS

Renee Parente Tutorial Co-Chair	Keith Serrels User Group Co-Chair
Ted Kolasa Tutorial Co-Chair	Daminda Dahanayaka User Group Co-Chair
Anita Madan Panel Discussion Co-Chair	Vinod Narang Roadmap Chair
Erwin Hendarto Panel Discussion Co-Chair	Becki Watt Expo Co-Chair
Rosalinda Ring Expo Co-Chair	Rosalinda Ring Movie Chair
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Chaun Zhang University Chair	Javeck Verdugo Local Arrangements Chair

ISTFA 2022 TECHNICAL PROGRAM COMMITTEE



ISTFA 2022 Technical Program Chair

Dr. Yan Li

Intel

Session Chairs

AI Applications for FA Sebastian Brand, <i>Fraunhofer Institute for Microstructure of Materials and Systems</i> Daminda Dahanayaka, <i>GLOBALFOUNDRIES</i>	FIB Circuit Analysis and Edit Rose Ring, <i>Howard Hughes Research Labs</i> Alex Buxbaum, <i>CARL ZEISS INC</i>	Package Level Fault Isolation Stephen Fasolino, <i>Global Foundries</i> Daniel Braun, <i>BMW AG</i>
Board and System Level FA John Bescup, <i>Jet Propulsion Laboratory</i> Jason Wheeler, <i>Raytheon</i>	FIB Sample Preparation Cathy Vartuli, <i>Butterfly Network</i> Valerie Brogden, <i>University of Oregon</i>	Packaging and Assembly Level FA Sherwin Tang, <i>TSMC</i> Sarah Wozny, <i>Applied Materials</i>
Case Studies: Device Analysis Gregory Johnson, <i>ZEISS Microscopy</i> Yuyan Wang, <i>Texas Instruments</i>	Hardware Attacks, Security, and Reverse Engineering Kevin Awai, <i>Mellanox</i> Mike Bruce, <i>Independent</i>	Product Yield, Test and Diagnostics Jayant D'Souza, <i>Mentor</i> David Pivin, <i>Intel</i>
Case Studies: FA Processes Wentao Qin, <i>ON Semiconductor</i> Juntao Li, <i>IBM Research</i>	Microscopy and Material Analysis I Wenbing Yun, PhD, <i>Sigray, Inc. Curtis Schreck, Analog Devices</i>	Sample Preparation and Device Deprocessing Peng Li, <i>Intel Corp</i> Christopher H. Kang, <i>Thermo Fisher Scientific</i>
Die Level Fault Isolation Dan Bodoh, <i>NXP Semiconductors</i> Lesly Endrinal, <i>Qualcomm Technologies Inc</i>	Microscopy and Material Analysis II Wenbing Yun, PhD, <i>Sigray, Inc. Curtis Schreck, Analog Devices</i>	Scanning Probe Analysis I & II Paiboon Tangyonyang, <i>Sandia Labs</i> Phil Kaszuba, <i>Globalfoundries</i>
Emerging FA Techniques and Concepts Kah Chin Cheong, <i>Samsung Austin Semiconductor</i>	Nanoprobng and Electrical Characterization David Albert, <i>IBM (Retired)</i> John Sanders, <i>Thermo Fisher Scientific</i>	3D Devices Failure Analysis William Lo, <i>NVIDIA Corporation</i> Eckhard Langer, <i>Globalfoundries</i>

Session Chairs – User Groups & Tutorials

<p>FIB User Group Valerie Brogden, <i>University of Oregon</i> Steven B. Herschbein, <i>GLOBALFOUNDRIES</i> Michael Wong, <i>Thermo Fisher Scientific</i> E.L. Principe, <i>Synchrotron Research Inc.</i></p>	<p>Nano/Scanning Probe User Group Greg Johnson, <i>GLOBALFOUNDRIES</i> Nicholas Antoniou, <i>Primenano Inc.</i></p>	<p>OFI/Test/ Diagnosis User Group Bryan Tracy, PhD, <i>Carl Zeiss Microscopy</i> Lihong Cao, <i>Advanced Micro Devices</i> Kevin A. Distelhurst, <i>GLOBALFOUNDRIES</i> Wentao Qin, <i>ON Semiconductor</i></p>
<p>Sample Preparation User Group Jim Colvin, Consultant Nathan Bakken, PhD, <i>Intel Corporation</i> Cecile S. Bonifacio, E.A. <i>Fischione Instruments, Inc</i> Kah Chin Cheong, <i>Onsemi</i></p>	<p>Electrical and Yield Tutorial Randal E. Mulder, <i>Silicon Labs</i> Gregory Johnson, <i>Carl Zeiss Microscopy</i></p>	<p>Fault Isolation I & II Tutorial Arun Karunanithi, <i>Advanced Micro Devices, Inc</i> Joseph Caroselli, <i>Advanced Micro Devices, Inc.</i></p>
<p>Microscopy I & II Tutorial Lorenz Lechner, <i>Kleindiek Inc.</i> Rose Ring, <i>Howard Hughes Research Labs</i></p>	<p>Package and Physical Analysis Challenge I & II Tutorial Bernice Zee, <i>Advanced Micro Devices (AMD)</i> Sarah Wozny, <i>Intel</i></p>	<p>Technology Specific and Featured I & II Tutorial John Bescup, <i>Jet Propulsion Laboratory</i> Corey Senowitz, <i>Qualcomm Technologies Inc.</i></p>